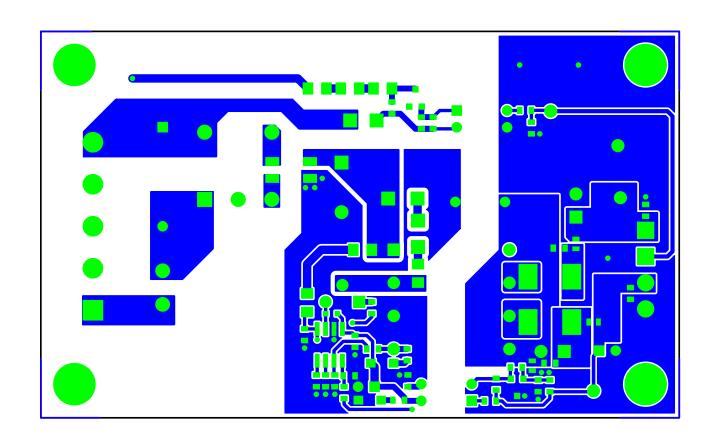
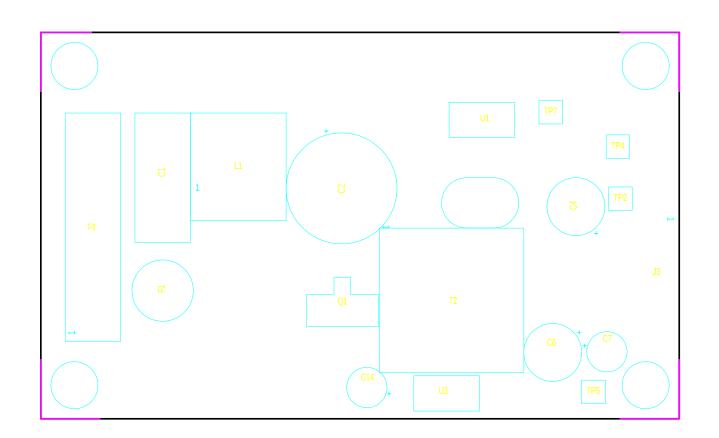


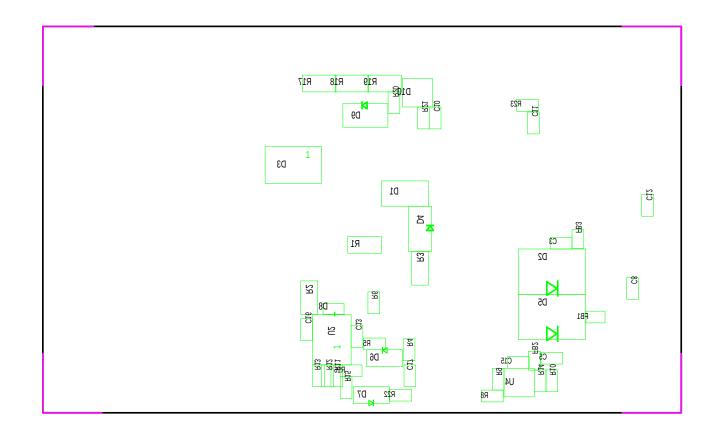
TEXAS INSTRUME	Copper	Copper Layer Name		Silkscreen		S Mask		P Mask		mbly	Fab Drawing	
TEXAS INSTITUTENTS		Тор	Top Bot Top Bot Top Bot To		Top	Bot	Тор	Bot	i ab blawing			
Board No. {Project Number}	Rev. <b>A</b>	L1										
Date: {Start Date} Filename: PMP8259A.PC	Engineer: B.KIN0	Pi	CB Dsgnr: R.SMITH	Modified	l Date: {	Modification	Date}				Software	PADs v9.3



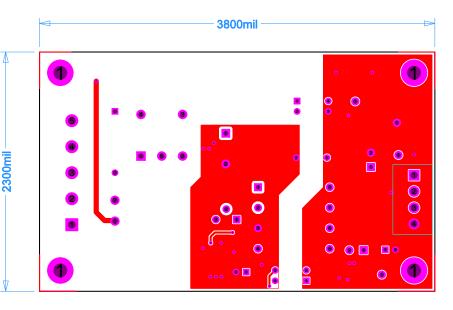
TEXAS INSTRUMENTS		Copper Layer Name		Silkscreen		S Mask		P Mask		Assembly		Fab Drawing	
		Тор	Bot	Тор	Bot	Тор	Bot	Top	Bot	Top	Bot	1 ab Brawing	
Board No. {Project Numbe		Rev. A		L2									
Date: {Start Date} Filename: Pi	MP8259A.PCB	Engineer: B.KING	P(	CB Dsgnr: R.SMITH	Modi	fied Date:	Modification	Date}				Software	PADs v9.3



TEXAS INSTRUMENTS			Сорр	Copper Layer Name		Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
TEXAS INSTITUTION		Тор		Bot	Тор	Bot	Top	Bot	Top	Bot	Тор	Bot	. Tab blawing	
Board No. {Project Nur	nber}	Rev. <b>A</b>	L1									TA		
Date: {Start Date} Filenam	e: PMP8259A.PCB	Engineer: B.KI	NG	PCB Dsgnr	R.SMITH	Modif	ied Date: {	Modification	Date}				Software	PADs v9.3



TEXAS INSTRUMENTS	Copper Layer Name		Silkscreen		S Mask		P Mask		Assembly		Fab Drawing		
TEXAS INSTITUTENTS		Top	Bot	Тор	Bot	Top	Bot	Тор	Bot	Тор	Bot	T ab Drawing	
Board No.  {Project Number}	<b>А</b>		L2								ВА		
Date: {Start Date} Filename: PMP8259A.PCB	Engineer: B.KING	PC	B Dsgnr: R.SMITH	Modif	ied Date: {	Modification	Date}				Software	PADs v9.3	



TEXAS INSTRUMENTS		Copper Layer Name		Silkscreen		S Mask		P Mask		Assembly		Fab Drawing		
		Top Bot		Bot	Тор	Bot	Top Bot		Тор	Bot	Тор	Bot	rab Diawing	
Board No. {Project	t Number}	Rev. A	L1											FB
Date: {Start Date}	Filename: PMP8259A.PCB	Engineer: B.KING		PCB (	Osgnr: R.SMITH	Mod	ified Date:	Modification	Date}				Software	PADs v9.3

	FABRICA	TION CHART				
FINISHED THICKNESS	SILKSCREEN	SOLDERMA	SK	FINISHED COPPER WEIGHT		
0.031	LAYER 1	LAYER 1		☐ 1 OZ.		
0.062	LAYER 2	LAYER 2		<b>2</b> OZ.		
0.093	NONE	□ NONE		OTHER		
□ 0.125						
DESIGN	TRACE/GAP S	SPACING	LAYER COUNT			
SMD	0.010/0.010			SINGLE SIDED		
☐ THRU-HOLE	0.008/0.007		2 LAYER			
MIX	0.006/0.006			4 LAYER		
				OTHER		

## NOTES: UNLESS OTHERWISE SPECIFIED

12. PANEL BORDER:

13. PROCESS CHANGES:

IN	UIES: UNLESS UI	HERWISE SPECIFIED
	MATERIAL:	ALL MATERIALS, INCLUDING BUT NOT LIMITED TO BASE LAMINATE, BONDING MATERIALS AND SOLDERMASK COATINGS FORMING THE FINISHED PRINTED CIRCUIT BOARD SHALL MEET UL-796 REQUIREMENTS AND BE ROHS COMPLIANT AND HAVE A FLAMMABILITY OF UL94V-0. PLASTIC SHEET, LAMINATED METAL CLAD, ONE OR TWO SIDES, BASE MATERIAL NEMA TYPE FR-4 OR
2.	BASE LAMINATE:	EQUIVALENT, W/Tg =140 Deg C OR HIGHER. MINIMUM DECOMPOSITION TEMP (Td) OF 320 Deg c. GLASS EPOXY RESIN, COPPER-CLAD IN ACCORDANCE WITH 2 LAYER STACK-UP, COMPLIANT WITH LEAD FREE PROCESS.
3.	SOLDERMASK:	SOLDERMASK OVER BARE COPPER (SMOBC) USING LIQUID PHOTO-IMAGEABLE SOLDERMASK IN ACCORDANCE WITH IPC-SM-840. COLOR: GREEN. MINOR SOLDERMASK ADJUSTMENTS TO FACILITATE PCB FAB AND OR ASSEMBLY IS ALLOWED PROVIDED NO DEFECTS ARE CREATED TO FINAL ASSEMBLY AS A RESULT.
4.	TOLERANCES:	UNLESS OTHERWISE SPECIFIED PCB TOLERANCES SHALL BE +/005 INCHES, HOLE DIAMETERS SHALL BE +/003 INCHES.
5.	PLATING:	HOLES REQUIRING PLATING, SEE HOLE CHART, TO HAVE 1 OZ. (0.0014) MIN. THK MIN. THICK COPPER.
6.	FINISH:	PLATE WITH ROHS COMPLIANT, IMMERSION SILVER PREFERRED, IMMERSION TIN OR Sn/Ag/Cu, WITH RMA FLUX, 0.0003" to .0005" THICK ALL EXPOSED AREAS AS COATED, NO ACTIVE FLUXES ARE ACCEPTABLE.
7.	LEGEND:	IF REQUIRED, SILKSCREEN LEGEND(S) WITH WHITE NON-CONDUCTIVE EPOXY INK.
8.	MARKINGS:	BOARD MUST BEAR VENDOR'S IDENTIFICATION CODE (ETCH OR WHITE NON-CONDUCTIVE INK). LOCATION OPTIONAL.
9.	WORKMANSHIP:	BOARD IS TO BE MANUFACTURED PER IPC-A-600 CLASS 2 REQUIREMENTS OR BETTER.
0.	DOCUMENTATION:	PCB VENDOR IS REQUIRED TO RETURN ANY AND ALL DOCUMENTS SUPPLIED OR ULTIMATELY PURCHASED BY TEXAS INSTRUMENTS UPON COMPLETION OF PURCHASE ORDER.
1.	DRILL SIZES:	HOLE DIAMETERS SHOWN ARE FINISHED SIZES AFTER PLATING UNLESS OTHERWISE NOTED.

ANY METAL IN BORDER AREA INCLUDING PART NUMBER, DATECODE AND/OR REVISION LETTERS MUST BE COVERED WITH SOLDERMASK.

NO DIMENSIONAL, MATERIAL, OR PROCESS CHANGES ARE ALLOWED WITHOUT PRIOR EXPLICIT WRITTEN PERMISSION FROM TEXAS INSTRUMENTS.

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